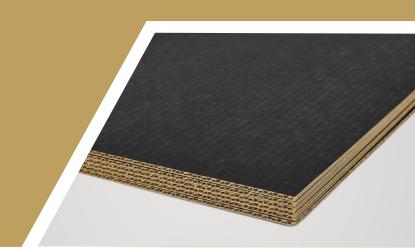


# CORSTAT

PN: CORSTAT

**DESCRIPTION:** Conductive Corrugated **APPLICATION:** Long-Term Use



### MATERIAL INFO

Corstat is CCI's proprietary conductive corrugated. It is an economical and highly effective static shielding material when formed into an enclosed box. It is very low sulfur and can be grounded at an ESD safe workstation so this is an excellent way to eliminate plain corrugated form an ESDA.

# **CHARACTERISTICS**

- <10<sup>5</sup> buried layer for shielding
- 10<sup>4</sup>-10<sup>5</sup> surface layer prevent sloughing
- Can be die cut, scored and printed
- Low sulfur

# **APPLICATIONS**

- ESD safe PCB partitioned totes
- Static safe bins and trays
- Shelf liners
- Component shippers



# **SPECIFICATIONS**

PROPERTY	VALUE (U.S.)	TEST METHOD
Color	Black	Visual
Surface Resistance		
Burried Shielding-layer Ohms	10 <sup>2</sup> -10 <sup>3</sup> Ohms/sq	ANSI/ESD STM11.11-2022
Outer Dissipative-layer Ohms	10 <sup>4</sup> -10 <sup>5</sup> Ohms/sq	ANSI/ESD STM11.11-2022
Electrostatic Decay Rate	Avg. 0.01 sec	EIA-541
ESD Shielding	Avg. 16.49nJ	Capacitative Probe Test
Reducible Sulphur	.00035%	TAPPI-406

# All values are for pre-formed materials. Electrical values will vary with each individual design.

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